

RPD Series

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The Merit Sensor RPD Series uncompensated packaged sensor is designed for the application of a wide range of pressures to the backside of the sensing element. The RPD is a flexible platform with excellent media compatibility. Its small, compact design is ideally suited for medical and industrial applications.

COMPANY: Merit Sensor designs and fabricates MEMS piezoresistive pressure sensors at our Utah, USA engineering and fabrication facility. We focus on the customization of technically superior pressure sensors to solve customers' pressure sensing needs for the medical, industrial, automotive and aerospace industries.

TECHNOLOGY: Merit Sensor utilizes a piezoresistive Wheatstone bridge with a chemically etched silicon diaphragm. All products are RoHS compliant.

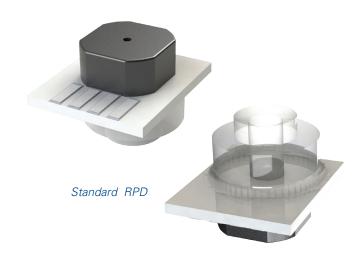
CAPABILITIES: Merit Sensor designs, engineers, fabricates, dices, assembles and tests all products from a state-of-the-art facility near Salt Lake City, Utah.

FFATURES

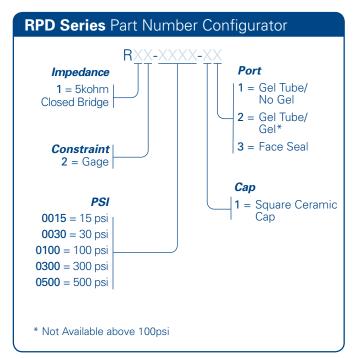
- · Uncompensated, packaged pressure sensor
- Pressure Range: 0 to 500psi (0 to 34.474bar)
- Typical average full scale output: 150 mV
- Size: 7.6 x 8.9 x 6.6 mm
- Temperature Range: -40°C to +85°C
- · Type: Backside gage
- Media: Air, gases and liquids (to be determined on an application-by-application basis with Merit engineering team)
- · Shipping: Tape and reel
- · Customization: Pressure range, pressure port
- Excellent performance in both constant current and constant voltage applications
- Simple pressure source attachment and electrical connection
- Designed for a soldered connection to wires, ribbon cable, or flex strip

APPLICATION EXAMPLES

- Medical inflation
- · Water pressure and flow management
- · Industrial process control









SPECIFICATIONS

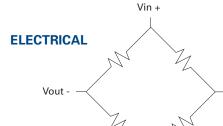
Parameter	Minimum	Typical	Maximum	Units	Notes
Electrical & Environmental					
Excitation (In)		5	15	V	Maximum: 3 mA
Impedance	4000	5000	6000	Ω	
Operating Temperature	-40		85	°C	Sentium® technology
Storage Temperature	-55		100	°C	
Performance					
Offset	-10	0	10	mV/V	Zero pressure; gage only; @25°C
Non-linearity	-0.2	0	0.2	% FSO	Best Fit Straight Line; @25°C
Pressure Hysteresis	-0.1	0	0.1	% FSO	@25°C
Temp Coeff – Zero	-25	0	25	μV/V/°C	-40°C to 85°C
Temp Coeff – Resistance	2300	2800	3300	PPM/°C	-40°C to 85°C
Temp Coeff – Sensitivity	-1500	-2200	-2500	PPM/°C	-40°C to 85°C
Thermal Hysteresis	-0.1	0	0.1	% FSO	Zero pressure
Burst Pressure	2X				Room Temperature
Full-Scale Output (@ 5 volts Excitation)					
15 psi (1 bar; 103 KPa)	60	75	90	mV	Closed bridge only
50 psi (3.4 bar; 345 KPa)	100	125	150	mV	
100 psi (6.9 bar; 689 KPa)	120	150	180	mV	
300 psi (20.7 bar; 2068 KPa)	120	150	180	mV	
500 psi (34.5 bar; 3447 KPa)	140	175	210	mV	

DIMENSIONS (millimeters)

to the substrate centerline Long axis: 0.6 Short axis: 0.0 R.2.9 -Out-7.6 3.8 Centerline -In of solder pads Pad dimensions: 8.9 0.7 W 2.2 L 1.3 Centerline Pad pitch: 1.3 of solder pads

Cap placement tolerance measured from the cap centerline

Gel cup placement tolerance measured from the part centerlinet othe substrate centerline Long axis: 1.3 Short axis: 0.0



Vin -

Vout +

PACKAGING AND SHIPPING (millimeters)

